

DATASHEET

Technical Data Sheet High Power Infrared LED <u>EAIST3535A1</u>



Features

- Small package with high efficiency
- Peak wavelength $\lambda p=940$ nm
- Soldering methods:SMT
- Thermal resistance (junction to lead): 11°C/W.
- Pb free
- The product itself will remain within RoHS compliant version.

Descriptions

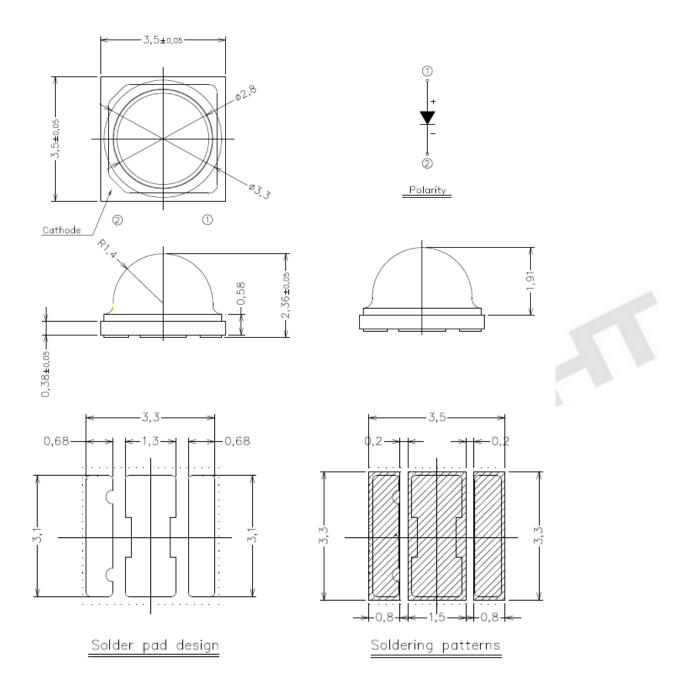
- EAIST3535A1 series is an infrared emitting diode in miniature SMD package which is molded in a water clear silicone with spherical top view lens.
- The device is spectrally matched with silicon photodiode, Phototransistor.

Applications

- CCD Camera
- Infrared applied system



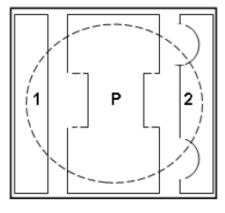
Package Dimensions



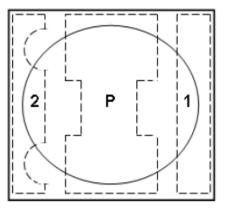
- 1. Dimensions are in millimeters.
- 2. Tolerances unless mentioned are ± 0.1 mm.
- 3. Do not handle the device by the lens. Incorrect force applied to the lens may lead to the failure of devices.



Pad Configuration



BOTTOM VIEW



TOP VIEW

PAD	FUNCTION
1	ANODE
2	CATHODE
Р	THERMAL PAD

Absolute Maximum Ratings (Ta=25°C)

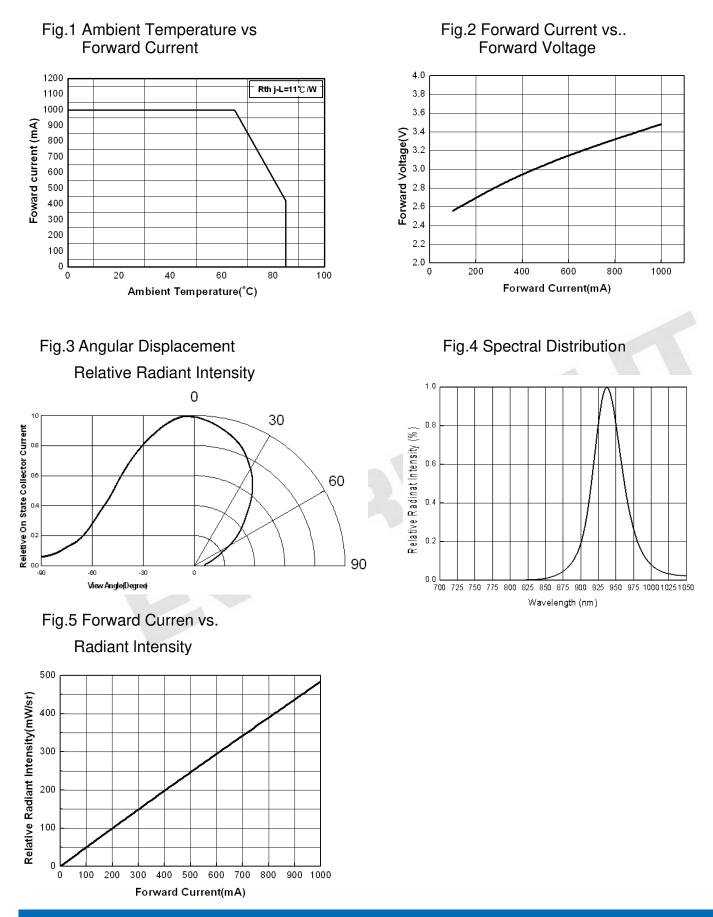
The solute maximum manings (10-20 C)						
Parameter	Symbol	Rating	Unit			
Forward Current	$I_{\rm F}$	1	А			
Reverse Voltage	V _R	5	V			
Operating Temperature	T _{opr}	-40 ~ +85	°C			
Storage Temperature	T _{stg}	-40 ~ +100	°C			
Junction temperature	Tj	115	°C			
Thermal resistance (junction to leadframe)	$R_{th(j-L)}$	11	°C/W			
Power Dissipation @I _F =1000mA	P _d	3.7	W			

Note: We suggest that customer should add the heat sink with EAIST3535A1 to exclude the heat.

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
		IF=350mA		370		
Total Radiated Power	Ро	IF=700mA		740		mW
		IF=1A		1070		
		IF=350mA	150	170		
Radiant Intensity	IE	IF=700mA	330	350		mW/sr
		IF=1A	450	470		
Peak Wavelength	λp	IF=350mA		940		nm
Spectral Bandwidth	Δλ	IF=350mA		25		nm
		IF=350mA		3.1		
Forward Voltage	VF	IF=700mA		3.4	-	V
		IF=1A		3.7	ł	
Reverse Current	IR	VR=5V			10	μA
View Angle	201/2	IF=20mA		90		deg

Typical Electro-Optical Characteristics Curves

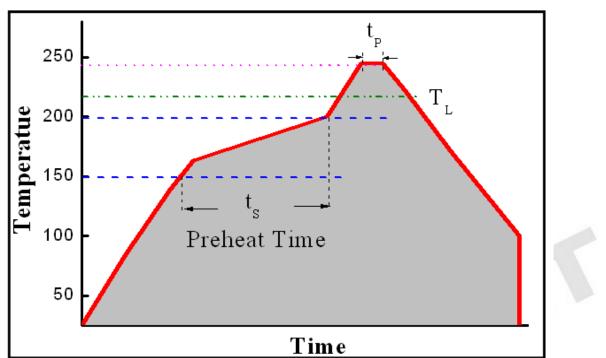


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Reflow Soldering Characteristics

For Reflow Process

- 1. EAIST3535A1 series are suitable for SMT processes.
- 2. Curing of glue in oven must be according to standard operation flow processes.



Profile Feature	Lead Free Assembly
Ramp-Up Rate	2-3 °C/S
Preheat Temperature	150-200 ℃
Preheat Time (t _s)	60-120 S
Liquid Temperature (T _L)	217 ℃
Time maintained above T_L	60-90 S
Peak Temperature (T _P)	240±5 ℃
Peak Time (t _P)	Max 20 S
Ramp-Down Rate	3-5 ℃/S

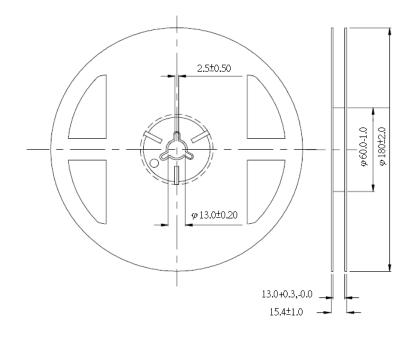
3. Reflow soldering should not be done more than twice.

4. In soldering process, stress on the LEDs during heating should be avoided.

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Package Dimensions

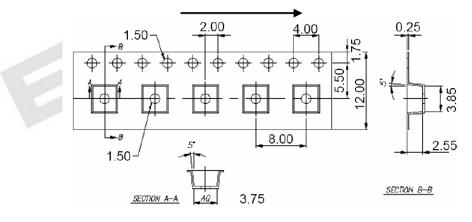


Note: 1. Dimensions are in millimeters

2. The tolerances unless mentioned is ±0.1mm

Carrier Tape Dimensions: Loaded quantity 400 PCS per reel.

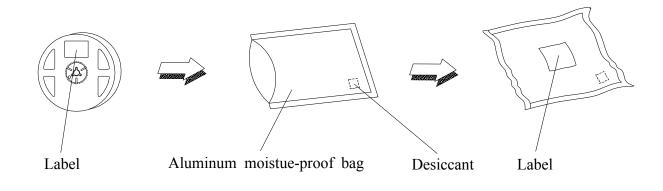
Feed Direction



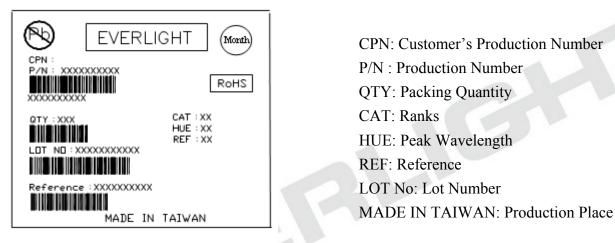
Note: 1. Dimensions are in millimeters

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Moisture Resistant Packaging



Label Form Specification



Notes

- 1. Above specification may be changed without notice. Everlight Americas will reserve authority on material change for above specification.
- 2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. Everlight Americas assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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